

**General Description**

The SJF30N042 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a wide variety of applications.

Features

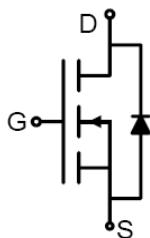
- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handing capability
- Lead free product is acquired

Application

- Load switch
- PWM applications
- Power management

Key Performance Parametes

Parameter	Value	Unit
V_{DS}	30	V
$R_{DS(ON)}_{TYP}$	4.3	$m\Omega$
I_D	99	A
Q_G	25	nC



Schematic Diagram



TO-220 top view

Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJF30N042	SJF30N042	TO-220	Tube	\	\	1000 Pcs

Table 1. Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V_{DS}	Drain-Source Voltage ($V_{GS}=0V$)	30	V
V_{GS}	Gate-Source Voltage ($V_{DS}=0V$)	± 20	V
I_D	Drain Current-Continuous($T_c=25^\circ C$)	99	A
	Drain Current-Continuous($T_c=100^\circ C$)	62	A
I_{DM} (pulse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	396	A
P_D	Maximum Power Dissipation($T_c=25^\circ C$)	83	W
	Maximum Power Dissipation($T_c=100^\circ C$)	33	W
E_{AS}	Avalanche energy (Note 2)	132	mJ
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 150	°C

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		1.5	°C/W



30V N-Channel Trench Power MOSFET

Table 3. Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ $I_{\text{D}}=250\mu\text{A}$	30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=30\text{V}$, $V_{\text{GS}}=0\text{V}$ $T_J=25^\circ\text{C}$			1	μA
		$V_{\text{DS}}=30\text{V}$, $V_{\text{GS}}=0\text{V}$ $T_J=125^\circ\text{C}$			100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$			± 100	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_{\text{D}}=250\mu\text{A}$	1		2.5	V
g_{FS}	Forward Transconductance	$V_{\text{DS}}=5\text{V}$, $I_{\text{D}}=20\text{A}$		32		S
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance	$V_{\text{GS}}=10\text{V}$, $I_{\text{D}}=15\text{A}$ $T_J=25^\circ\text{C}$		4.3	5.4	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_{\text{D}}=10\text{A}$ $T_J=25^\circ\text{C}$		6.2	8.1	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1.0\text{MHz}$		1730		pF
C_{oss}	Output Capacitance			192		pF
C_{rss}	Reverse Transfer Capacitance			171		pF
R_g	Gate resistance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=0\text{V}$, $f=1.0\text{MHz}$		1.1		Ω
Switching Parameters						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{GS}}=10\text{V}$, $V_{\text{DS}}=15\text{V}$, $R_L=1\Omega$, $R_{\text{GEN}}=3\Omega$		11		nS
t_r	Turn-on Rise Time			55		nS
$t_{\text{d(off)}}$	Turn-Off Delay Time			198		nS
t_f	Turn-Off Fall Time			120		nS
Q_g	Total Gate Charge	$V_{\text{GS}}=10\text{V}$, $V_{\text{DS}}=15\text{V}$, $I_{\text{D}}=15\text{A}$		25		nC
Q_{gs}	Gate-Source Charge			5		nC
Q_{gd}	Gate-Drain Charge			10		nC
Source-Drain Diode Characteristics						
I_{SD}	Source-Drain Current (Body Diode)				99	A
V_{SD}	Forward on Voltage (Note 3)	$V_{\text{GS}}=0\text{V}$, $I_{\text{S}}=20\text{A}$			1.2	V
t_{rr}	Reverse Recovery Time	$I_{\text{F}}=20\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		12		ns
Q_{rr}	Reverse Recovery Charge	$I_{\text{F}}=20\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		4		nC

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

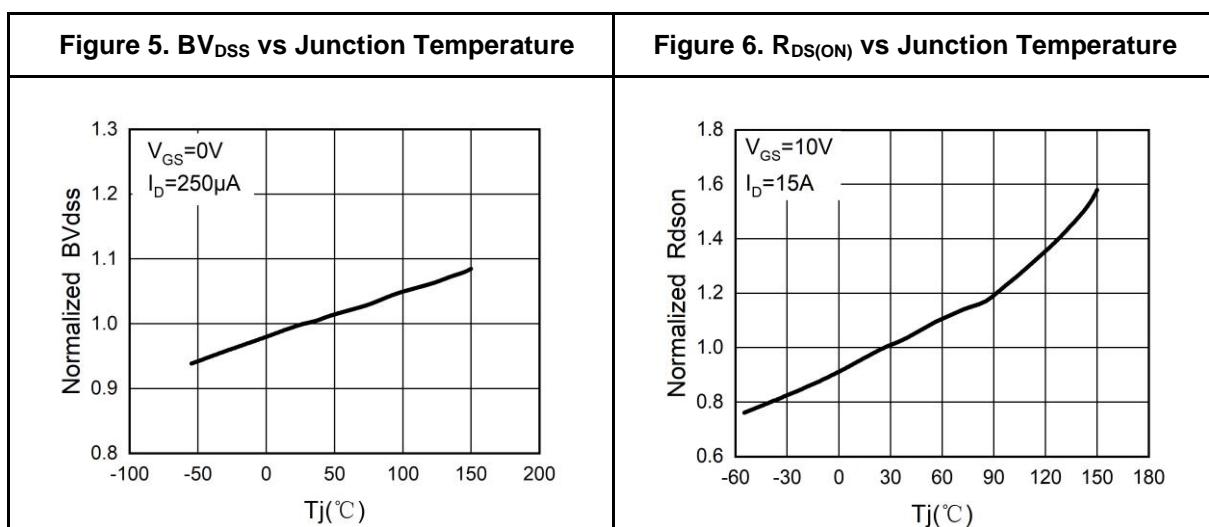
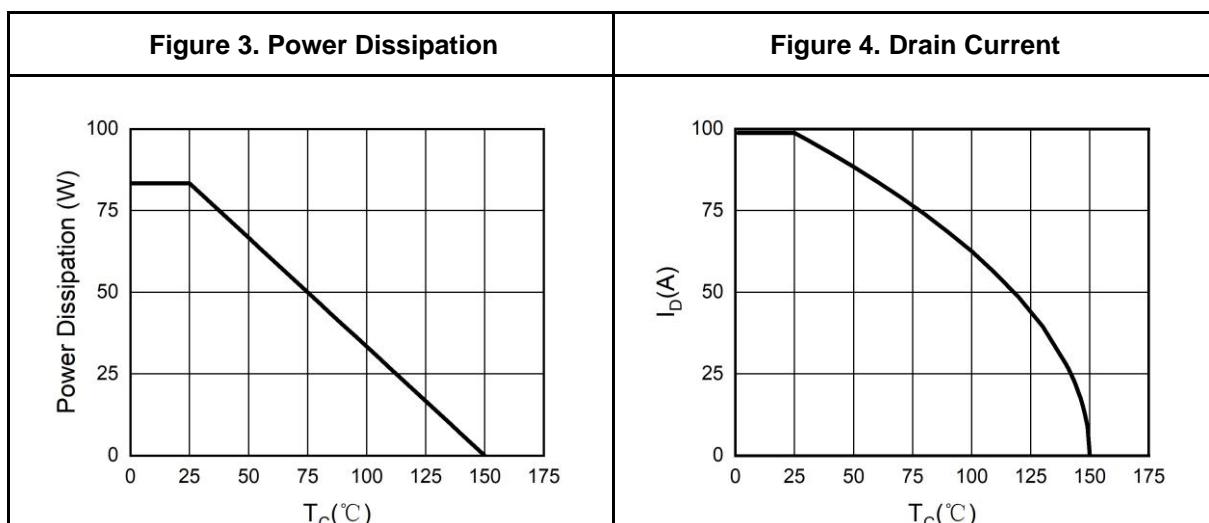
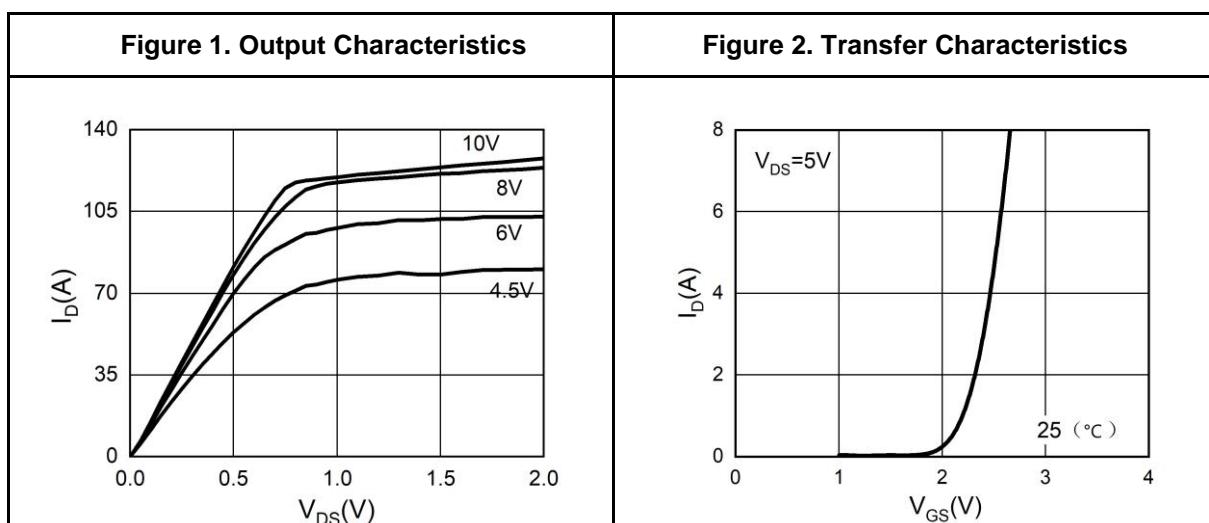
Notes 2.E_{AS} condition: $T_J=25^\circ\text{C}$, $V_{\text{DD}}=20\text{V}$, $V_G=10\text{V}$, $R_g=25\Omega$, $L=0.5\text{mH}$.

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.



30V N-Channel Trench Power MOSFET

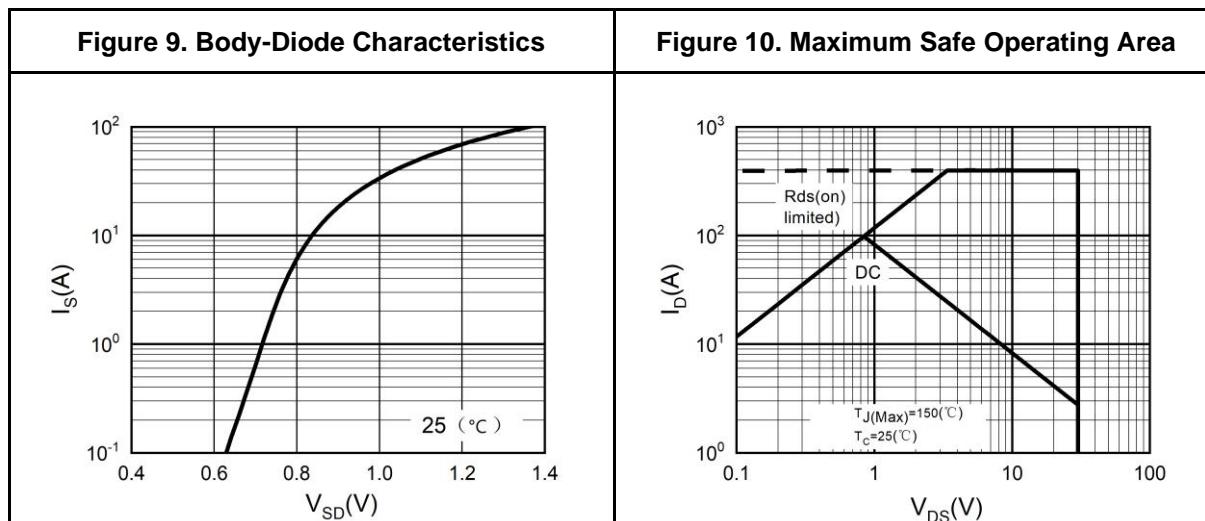
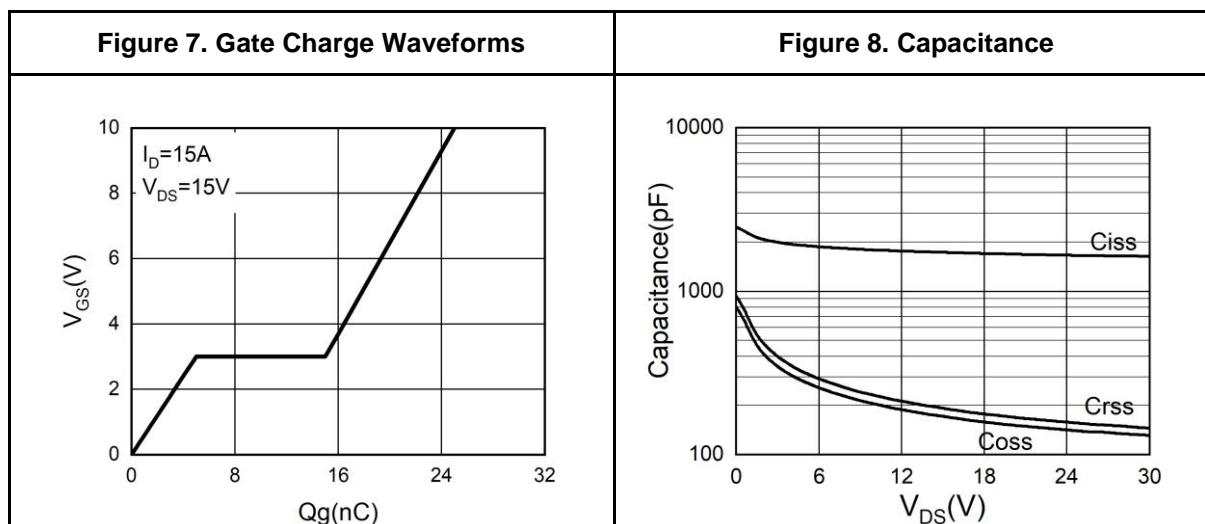
Typical Electrical And Thermal Characteristics (Curves)





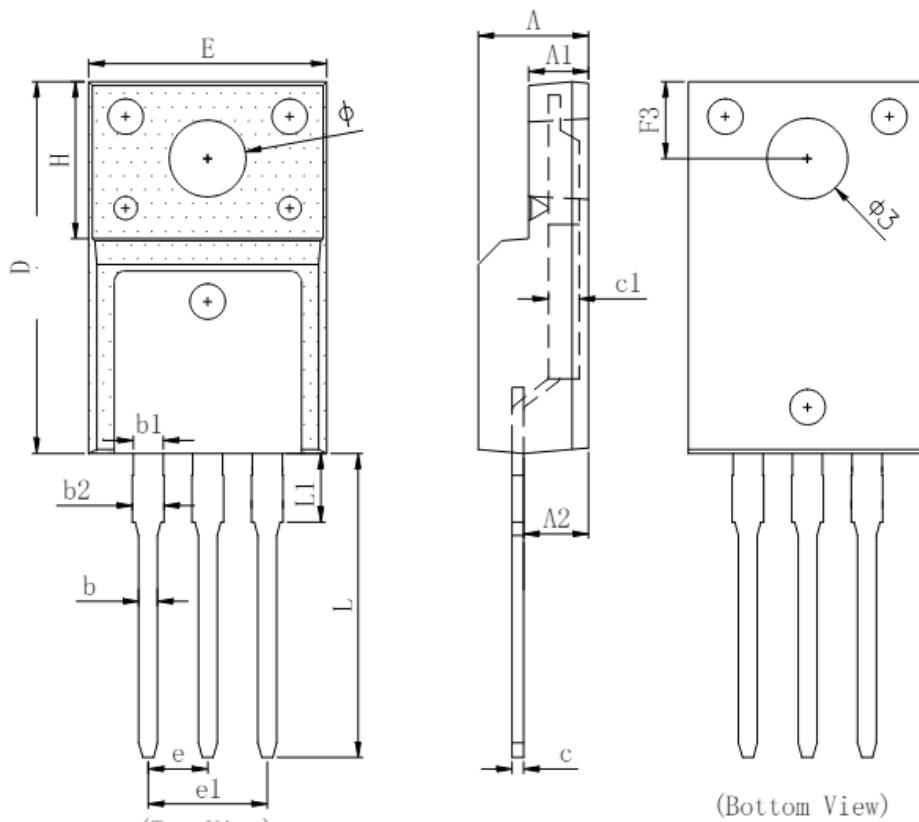
30V N-Channel Trench Power MOSFET

Typical Electrical And Thermal Characteristics (Curves)





TO-220F Package Information



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	4.500	4.700	4.900
A1	2.340	2.540	2.740
A2	2.560	2.760	2.960
b	0.700	0.800	0.950
b1	1.180	1.280	1.430
b2	1.250	1.350	1.550
c	0.400	0.500	0.650
c1	1.200	1.300	1.350
D	15.570	15.870	16.170
H	6.700 REF		
E	9.960	10.160	10.360
e	2.540 BSC		
e1	5.080 BSC		
L	12.680	12.980	13.280
L1	2.780	2.930	3.080
F3	3.150	3.300	3.450
φ	3.030	3.180	3.450
φ3	3.150	3.450	3.650

(注：全尺寸测量时c1不测)



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